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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/787,413	02/27/2004	Yukihiro Urakawa	249344US2SDIV	4542	
22850	7590 07/27/2005		EXAMINER		
OBLON, SPIVAK, MCCLELLAND, MAIER & NEUSTADT, P.C.			ABRAHAM, FETSUM		
	ALEXANDRIA, VA 22314		ART UNIT	PAPER NUMBER	
			2826		
				DATE MAILED: 07/27/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

			4H
	Application No.	Applicant(s)	
	10/787,413	URAKAWA, YUKIF	IIRO
Office Action Summary	Examiner	Art Unit	
	Fetsum Abraham	2826	
The MAILING DATE of this communication eriod for Reply	n appears on the cover sheet wi	th the correspondence add	iress
A SHORTENED STATUTORY PERIOD FOR RI THE MAILING DATE OF THIS COMMUNICATION Extensions of time may be available under the provisions of 37 Cf after SIX (6) MONTHS from the mailing date of this communication If the period for reply specified above is less than thirty (30) days, If NO period for reply is specified above, the maximum statutory properties to reply within the set or extended period for reply will, by some analysis and the set of the	ON. FR 1.136(a). In no event, however, may a ren. a reply within the statutory minimum of thirty eriod will apply and will expire SIX (6) MON statute, cause the application to become AB.	eply be timely filed y (30) days will be considered timely. THS from the mailing date of this cor ANDONED (35 U.S.C. § 133).	mmunication.
tatus	•		
1) Responsive to communication(s) filed on 2	27 April 2005.		
2a) ☐ This action is FINAL . 2b) ☑	This action is non-final.	•	
3) Since this application is in condition for all	owance except for formal matte	ers, prosecution as to the	merits is
closed in accordance with the practice und	der <i>Ex par</i> te Quayle, 1935 C.D	. 11, 453 O.G. 213.	
isposition of Claims			
4) Claim(s) 1-17 is/are pending in the applica	ation.		
4a) Of the above claim(s) is/are with			
5) Claim(s) is/are allowed.			-
6)⊠ Claim(s) <u>all</u> is/are rejected.			
7)⊠ Claim(s) <u>3 and 11</u> is/are objected to.			
8) Claim(s) are subject to restriction a	nd/or election requirement.		
pplication Papers			
9) The specification is objected to by the Example 1	miner.		
10) The drawing(s) filed on is/are: a)	accepted or b) objected to t	by the Examiner.	
Applicant may not request that any objection to	the drawing(s) be held in abeyan	ce. See 37 CFR 1.85(a).	
Replacement drawing sheet(s) including the co	prrection is required if the drawing(s) is objected to. See 37 CF	R 1.121(d).
11) The oath or declaration is objected to by the	e Examiner. Note the attached	Office Action or form PT	O-152.
riority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for for a) All b) Some * c) None of: 1. Certified copies of the priority docum 2. Certified copies of the priority docum 3. Copies of the certified copies of the application from the International But * See the attached detailed Office action for a	nents have been received. nents have been received in Appriority documents have been ureau (PCT Rule 17.2(a)).	oplication No received in this National S	Stage
·		•	
ttachment(s)			
Notice of References Cited (PTO-892)	4) Interview S	ummary (PTO-413)	
Notice of Draftsperson's Patent Drawing Review (PTO-948 Information Disclosure Statement(s) (PTO-1449 or PTO/SI)/Mail Date formal Patent Application (PTO	-152)
Paper No(s)/Mail Date	6) Other:	·	102)

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DETAILED ACTION

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1,4,7-10,12,16,17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Nagao (6,677,674) in view of Kimura et al (6,078,096) and further in view of Kim et al (6,594,818).

As for claims 1,7, the primary reference discloses the claimed COC package in fig. 7A where a memory chip (21) is mounted on logic chip (20) and both secured with each other with bump bonding means (2). a generic memory wafer having memory units separated by scribe lanes. Chips of different storage capacity are then extracted or produced from the wafer by combining different number of units similar to what the claimed invention does in figure 5 (see the abstract).

The primary reference discloses the most important portion of the claimed structure but could have missed detailing how the memory chips were separated from the memory wafer. However, Kimura et al teaches that chips were separated from a mother wafer by dicing means. Therefore, it would have been obvious to one skilled in the art to dice the chips in the primary reference from the mother wafer since dicing is the most basic and popular way of separating chips with high yield.

The prior arts disclose most subject matters claimed but may have missed to indicate that the memory chips were functionally mutually exclusive. However, Kim et al.

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teaches that mutually exclusive memory chips of different capacity can be extracted from unit chips formed in common mother wafer (see abstract). Therefore, it would have been obvious to one skilled in the art to separate unit cells in singularity or multiplicity based on desired memory capacity since the practice satisfies various memory capacity requirement of different memory systems in different devices.

As for claims 2,10, the chips in the last two patents are similar units.

As for claims 8,9, the logic circuits supporting the memory chips in the primary reference is capable of generating control signals that assign word and data bits that in turn change word bits as understood by the examiner but called by the applicant as "organization"

As for claims 4,12, "product by process" claims are directed to the product per se, no matter how actually made, In re Hirao, 190 USPQ 15 at 17 (footnote 3). See also In re Brown, 173 USPQ 685 and In re Thorpe, 227 USPQ 964, 966. Therefore, the way the product was made does not carry any patentable weight as long as the claims are directed to a device. Further, note that the applicant has the burden of proof in such cases, as the above case law makes clear. Also see MPEP 2113.

As for claim 16, the primary art is a SiP (System in Package) device because it packages two different chips in integration.

As for claim 17, figure 2 of the primary reference shows that the COC structure is well packaged and the chips covered with encapsulant material and a container that contains the overall system.

Claims 5,6,13,14,15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Nagao (6,677,674) in view of Kimura et al (6,078,096) and further in view of Kim et al (6,594,818) and further in view of Majima (4,408,875).

As for claims 5,13, although the shape of memory chips and length are known to be variable in the art and the specification indicates the arbitrary nature of the chosen size (see page 22, 18-20), the prior arts are silent on their chip shapes and length. However, Majima discloses a square memory chip having an area of 10 mm**2 (see column 2, 5-15). Therefore, it would have been obvious to one skilled in the art to form

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the claimed memory shape because they tend to be simpler for projector-type exposure processing and the selected length because high-precision exposure has limitations as chip sizes go smaller and smaller.

As for claims 6,14, dicing line width is inversely proportional to yield. It is a known function of the target number of chips yielded from a given wafer. Therefore, it is known to be variable in the art. The claimed width by itself is not patentable unless criticality is an issue. In this case, the specification contains no disclosure of either the critical nature of the claimed arrangement or any unexpected results arising therefrom. Where patentability is said to be based upon particular chosen dimensions or upon another variable recited in a claim, the applicant must show that the chosen dimensions are critical. In re Woodruff, 919 F.2d 1575, 1578, 16 USPQ2d 1934, 1936 (Fed. Cir. 1990). In fact, in pages 22 and 23, the width seems to have been picked arbitrarily and no teaching exists of its critical nature (see the last paragraph of page 23).

Claims 3 and 11 have been objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Fetsum Abraham whose telephone number is: 571-272-1911. The examiner can normally be reached on 8:00 - 18:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan J Flynn can be reached on 571-272-1915.